

10A, 2MHz, 2.7V to 16V Integrated Step-Down Switching Regulator with PMBus

MAX20810

General Description

The MAX20810 is a fully integrated, highly efficient, step-down DC-DC switching regulator with PMBus interface. The device operates from 2.7V to 16V input supplies, and the output can be adjusted from 0.4V to 5.8V, delivering up to 10A of load current.

The switching frequency of the device can be configured from 500kHz to 2MHz, to provide the capability of optimizing the design in terms of size and performance.

The MAX20810 utilizes fixed frequency, current-mode control with internal compensation. The IC features a selectable advanced modulation scheme (AMS) to provide improved performance during fast load transients. Operation settings and configurable features can be selected by connecting a pin-strap resistors from the PGM_ pins to ground or using PMBus commands.

The IC has an internal 1.8V LDO output to power the gate drives (V_{CC}) and internal circuitry (AVDD). The device also has an optional LDO input pin (LDOIN), allowing connection from a 2.5V to 5.5V bias input supply for optimized efficiency.

The IC has multiple protections including positive and negative overcurrent protection, output overvoltage protection, and overtemperature protection to ensure a robust design.

The device is available in 4.3mm x 6.55mm FC2QFN package. It supports -40°C to $+125^{\circ}\text{C}$ junction temperature operation. The MAX20810 is footprint compatible with the MAX20815 and MAX20830.

Applications

- Data Center Power
- Communications Equipment
- Networking Equipment
- Servers and Storage
- Point-of-Load Voltage Regulators

Ordering Information appears at end of data sheet.

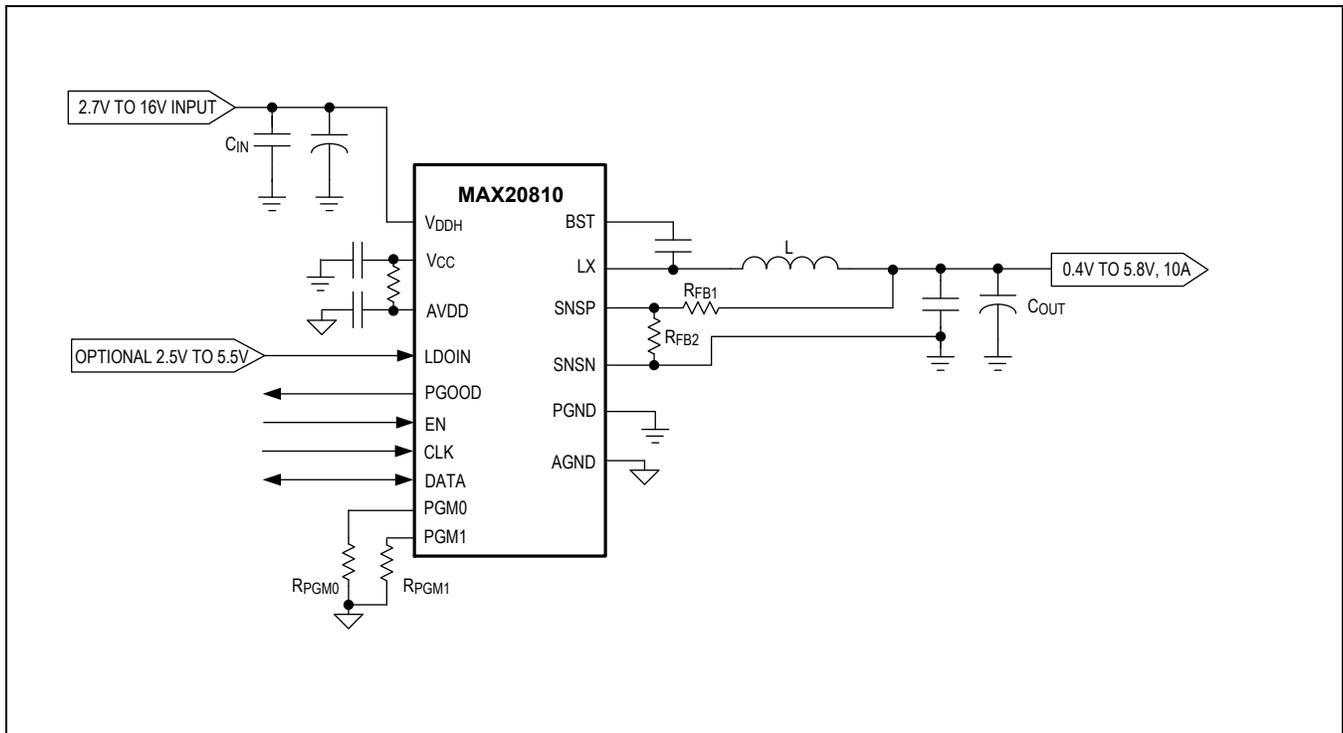
Benefits and Features

- High Power Density with Low Component Count
 - Compact 4.3mm x 6.55mm, 16-pin, FC2QFN Package
 - Internal Compensation
 - Single-Supply Operation with Integrated LDO for Bias Generation
- Wide Operating Range
 - 2.7V to 16V Input Voltage Range
 - 0.4V to 5.8V Output Voltage Range
 - 500kHz to 2MHz Configurable Switching Frequency
 - -40°C to $+125^{\circ}\text{C}$ Junction Temperature Range
- Optimized Performance and Efficiency
 - 93.8% Peak Efficiency with $V_{DDH} = 12\text{V}$ and $V_{OUT} = 1.8\text{V}$
 - High Efficiency with Optional External Bias Input Supply
 - AMS to Improve Load Transient Response
 - Differential Remote Sense
- PMBus Interface
 - Adaptive Voltage Scaling of 0.4V to 0.8V Reference Range
 - PMBus Telemetry of Output Current, Output Voltage, Input Voltage, and Junction Temperature

DESCRIPTION	CURRENT RATING* (A)	INPUT VOLTAGE (V)	OUTPUT VOLTAGE (V)
Electrical Rating	10	2.7 to 16	0.4 to 5.8
Thermal Rating $T_A = 55^{\circ}\text{C}$, 200LFM air flow	10	12	3.3
Thermal Rating $T_A = 85^{\circ}\text{C}$, no air flow	10	12	1.8

*Maximum $T_J = +125^{\circ}\text{C}$. For specific operating conditions, see the Safe Operating Area (SOA) curves in the [Typical Operating Characteristics](#) section.

Simplified Application Circuit



Absolute Maximum Ratings

V _{DDH} to PGND (Note 1)	-0.3V to +19V	V _{CC} to PGND	-0.3V to +2.5V
LX to PGND (DC)	-0.3V to +19V	AVDD to AGND	-0.3V to +2.5V
LX to PGND (AC) (Note 2)	-10V to +23V	LDOIN to AGND	-0.3V to +6V
V _{DDH} to LX (DC) (Note 1)	-0.3V to +19V	EN, PGOOD, CLK, DATA to AGND	-0.3V to +4V
V _{DDH} to LX (AC) (Note 2)	-10V to +23V	SN _{SP} , SN _{SN} to AGND	-0.3V to AVDD+0.3V
BST to PGND (DC)	-0.3V to +21.5V	PGM0, PGM1 to AGND	-0.3V to AVDD+0.3V
BST to PGND (AC) (Note 2)	-7V to +25.5V	Peak LX Current	-25A to +33A
BST to LX	-0.3V to +2.5V	Junction Temperature (T _J)	+150°C
PGND to AGND	-0.3V to +0.3V	Storage Temperature Range	-65°C to +150°C
		Peak Reflow Temperature Lead-Free	+260°C

Note 1: Input HF capacitors placed not more than 40 mils away from the V_{DDH} pin required to keep inductive voltage spikes within absolute maximum limits.

Note 2: AC is limited to 25ns

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Package Information

16 FC2QFN

Package Code	F164A6F+2
Outline Number	21-100528
Land Pattern Number	90-100191
Thermal Resistance	
Junction-to-Ambient (θ _{JA})	48.5 °C/W
Junction-to-Case Thermal Resistance (θ _{JC})	10.7 °C/W
Junction-to-Ambient Thermal Resistance (θ _{JA}) on MAX20810EVKIT# (no heat sink, no airflow)	18.1 °C/W

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

Electrical Characteristics

(See [Typical Application Circuit](#). $V_{DDH} = 12V$, $V_{LDOIN} = 3.3V$, $T_A = T_J = -40^{\circ}C$ to $+125^{\circ}C$, unless otherwise noted. Specifications are production tested at $T_A = +32^{\circ}C$; limits within the operating temperature range are guaranteed by design and characterization.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input Supply						
Input Voltage Range	V_{DDH}		2.7		16	V
Input Supply Current	I_{VDDH}	$V_{LDOIN} = 3.3V$, EN = AGND		0.12		mA
		$V_{LDOIN} = AGND$, EN = AGND		6.5		
Linear Regulator Input Voltage	V_{LDOIN}		2.5		5.5	V
Linear Regulator Input Current	I_{LDOIN}	$V_{LDOIN} = 3.3V$, EN = AGND		6.4		mA
Internal LDO Regulated Output	V_{CC}		1.71	1.80	1.95	V
Linear Regulator Current Limit		$V_{LDOIN} = AGND$	85	170		mA
		$V_{LDOIN} = 3.3V$	100	230		
		$V_{CC} < 1.6V$		25		
AVDD Undervoltage Lockout	AVDD	Rising	1.65	1.67	1.70	V
AVDD Undervoltage Lockout Hysteresis				55		mV
VDDH Undervoltage Lockout		Rising	2.4	2.5	2.6	V
VDDH Undervoltage Lockout Hysteresis				100		mV
LDOIN Undervoltage Lockout	V_{LDOIN}	Rising	2.26	2.33	2.40	V
LDOIN Undervoltage Lockout Hysteresis				100		mV
Output Voltage Range and Accuracy						
Feedback Voltage Accuracy	$V_{SNSP} - V_{SNSN}$	$V_{REF} = 0.4V$ to $0.8V$	-1		+1	%
		$V_{REF} = 0.5V$, $T_A = T_J = 0^{\circ}C$ to $+85^{\circ}C$	-0.6		+0.6	
Positive Voltage Sense Leakage Current	I_{SNSP}		-1		1	μA
Negative Voltage Sense Input Range	V_{SNSN}		-100		+100	mV
Negative Voltage Sense Bias Current	I_{SNSN}			300	550	μA
Switching Frequency						
Switching Frequency	F_{SW}			500		kHz
				600		
				750		
				1000		
				1200		
				2000		
Switching Frequency Accuracy			-10		+10	%
Minimum Controllable On-Time		Inductor valley current $\leq 0A$ (Note 3)		36	50	ns
		Inductor valley current $> 0A$ (Note 3)		30	45	

(See [Typical Application Circuit](#). $V_{DDH} = 12V$, $V_{LDOIN} = 3.3V$, $T_A = T_J = -40^{\circ}C$ to $+125^{\circ}C$, unless otherwise noted. Specifications are production tested at $T_A = +32^{\circ}C$; limits within the operating temperature range are guaranteed by design and characterization.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Minimum Controllable Off-Time		(Note 3)		100	140	ns
Enable and Startup						
Initialization Time	t_{INIT}			800		μs
EN Threshold		Rising	0.9			V
		Falling			0.6	
EN Filtering Delay		Rising		250		μs
		Falling		2		
Soft-Startup Slew Rate		$V_{SNSP} - V_{SNSN}$		0.5		V/ms
Power Good and Fault Protections						
PGOOD Output Low		$I_{PGOOD} = 4mA$			0.4	V
Output Undervoltage (UV) Threshold		$V_{REF} = 0.5V$	-16	-13	-10	%
Output UV Deglitch Delay				2		μs
Output Overvoltage Protection (OVP) Threshold		$V_{REF} = 0.5V$	10	13	16	%
Output OVP Threshold Deglitch Delay				2		μs
Positive Overcurrent Protection (POCP) Threshold		Inductor peak current, POCP = 15A	13.5	15	16.5	A
		Inductor peak current, POCP = 13A	11.7	13.0	14.3	
		Inductor peak current, POCP = 11A	9.9	11.0	12.1	
		Inductor peak current, POCP = 9A	8.0	9.0	9.9	
POCP Deglitch Delay	t_{POCP}			40		ns
Fast Positive Overcurrent Protection (FPOCP) Threshold			17.1	19	21.6	A
Negative Overcurrent Protection (NOCP) Threshold to POCP Threshold Ratio				-79		%
NOCP Accuracy			-20		+20	%
BST UVLO Threshold	V_{BST}		1.48	1.56	1.64	V
BST UVLO Threshold Hysteresis				52		mV
Overtemperature Protection (OTP) Rising Threshold				155		$^{\circ}C$
OTP Accuracy				6		%
OTP Hysteresis				20		$^{\circ}C$
Hiccup Protection Time		OVP, POCP or NOCP		20		ms
DCM Operation Mode						
DCM Comparator Threshold to Enter DCM		POCP = 15A, Inductor Valley Current		-0.75		A
		POCP = 13A, Inductor Valley Current		-0.67		

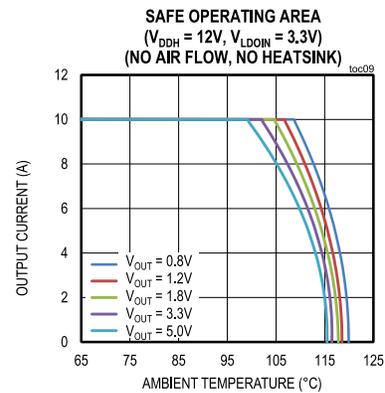
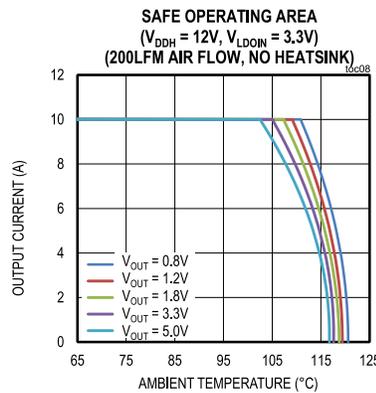
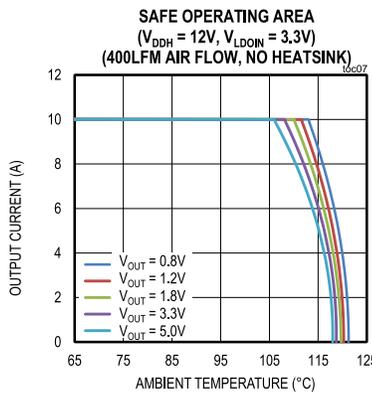
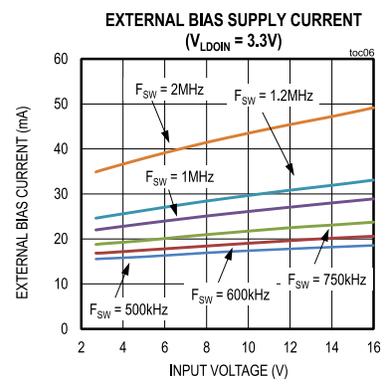
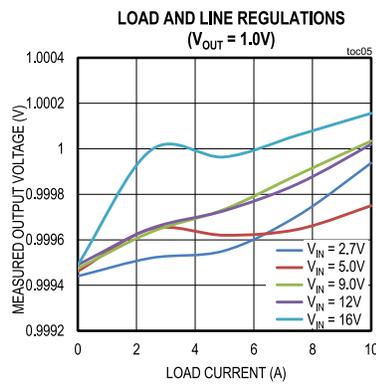
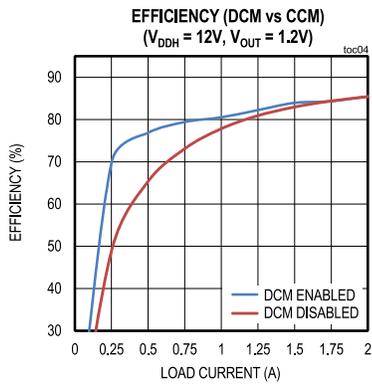
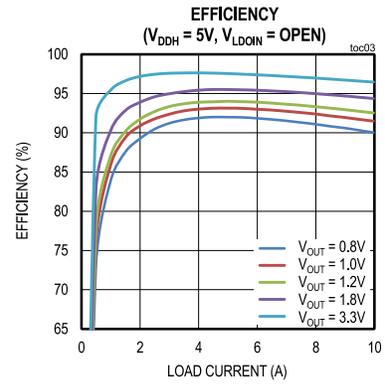
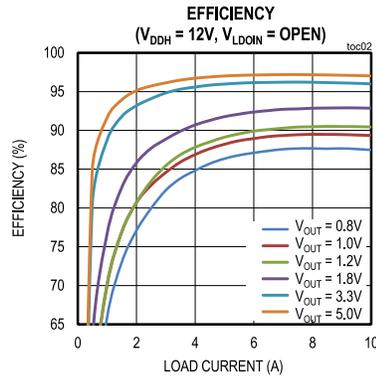
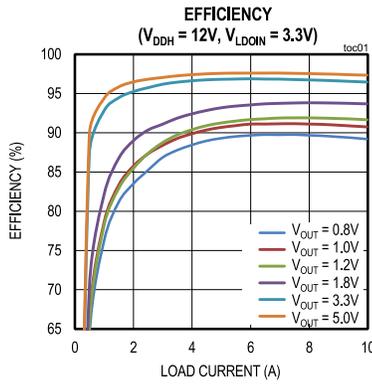
(See [Typical Application Circuit](#). $V_{DDH} = 12V$, $V_{LDOIN} = 3.3V$, $T_A = T_J = -40^{\circ}C$ to $+125^{\circ}C$, unless otherwise noted. Specifications are production tested at $T_A = +32^{\circ}C$; limits within the operating temperature range are guaranteed by design and characterization.)

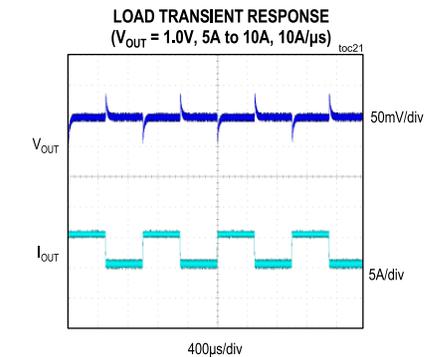
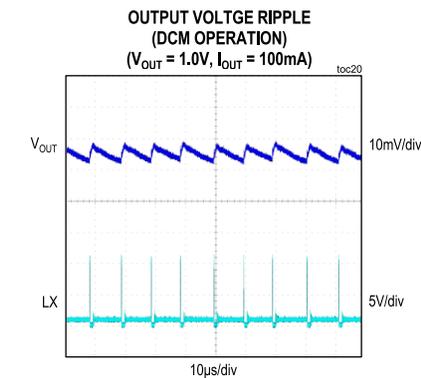
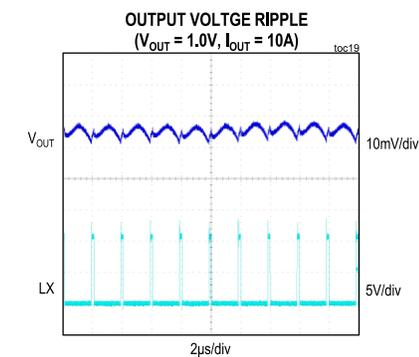
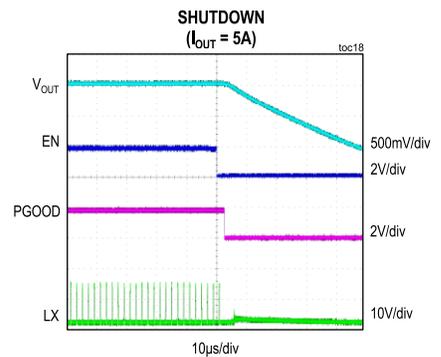
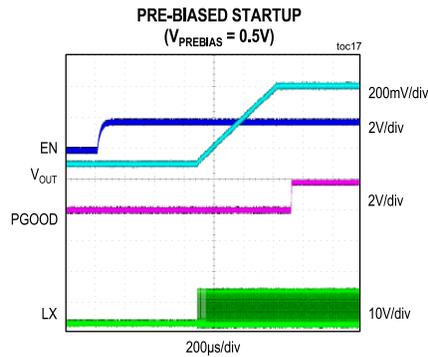
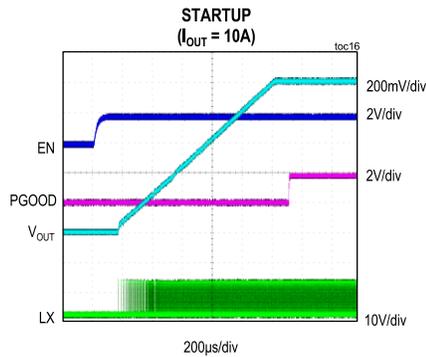
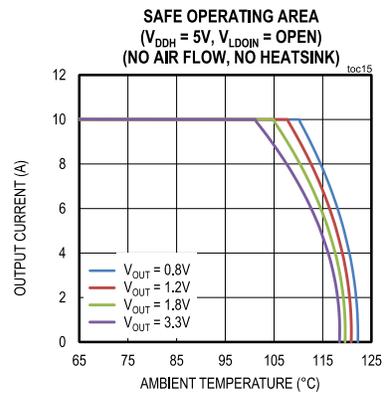
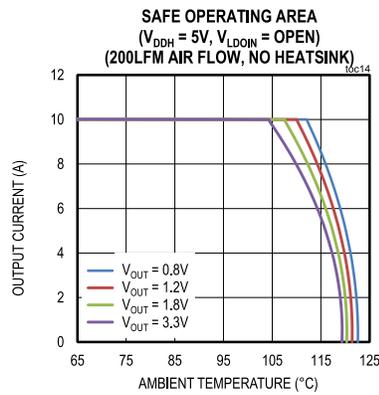
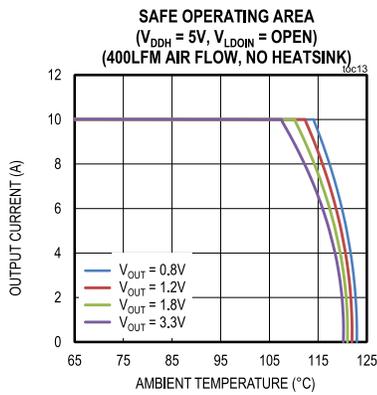
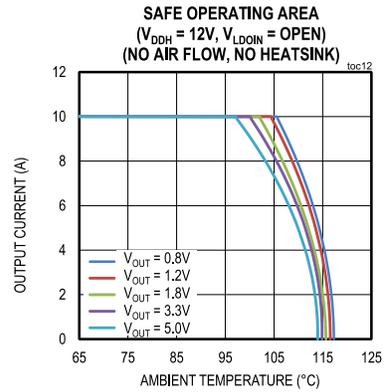
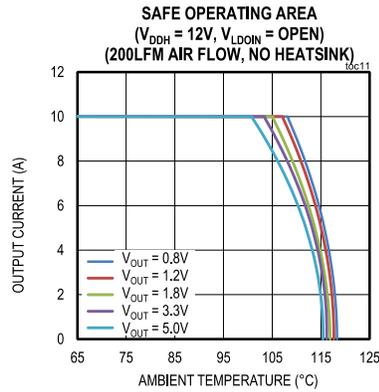
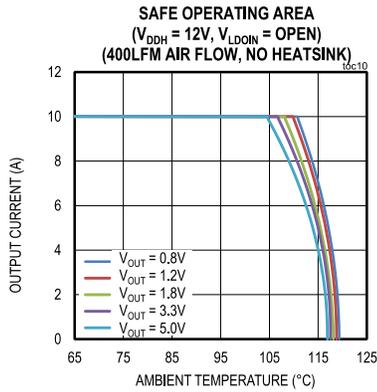
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
		POCP = 11A, Inductor Valley Current		-0.6		
		POCP = 9A, Inductor Valley Current		-0.45		
DCM Comparator Threshold to Exit DCM		Inductor Valley Current		0.07		A
PMBus Interface						
CLK, DATA Input Logic Low Voltage					0.8	V
CLK, DATA Input Logic High Voltage			1.45			V
CLK, DATA Input Leakage Current			-1		+1	μA
DATA Output Logic Low		Sinking 4mA			0.4	V
PMBus Operating Frequency	F_{CLK}				1000	kHz
PMBus Telemetry						
Reading Update Rate		READ_IOUT, READ_VOUT, and READ_VIN		1.47		ms
		READ_TEMPERATURE		2.86		
READ_IOUT Range			0		15	A
READ_IOUT Accuracy		$I_{OUT} = 0A$	-1		+1	A
		$0A < I_{OUT} < 15A$	-1.5		+1.5	
READ_VOUT Range			400		800	mV
READ_VOUT Accuracy			-1.5		+1.5	%
READ_VIN Range			2.3		16	V
READ_VIN Accuracy			-350		+350	mV
READ_TEMPERATURE Range			-40		150	$^{\circ}C$
READ_TEMPERATURE Accuracy				± 4		$^{\circ}C$
Programming Pins						
PGM_ Pin Resistor Range			0.095		115	k Ω
PGM_ Resistor Accuracy			-1		+1	%

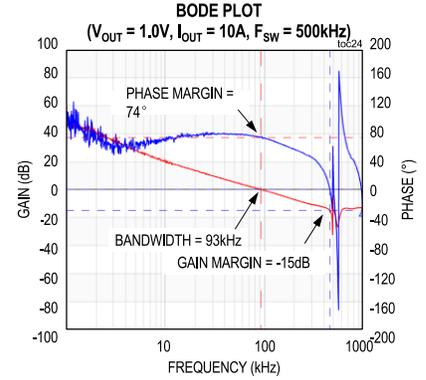
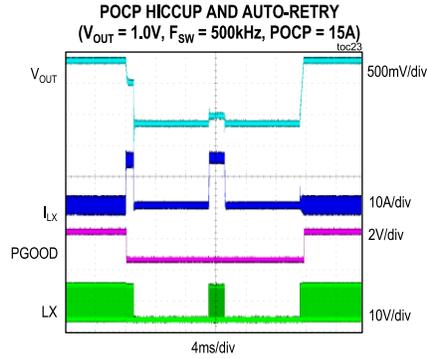
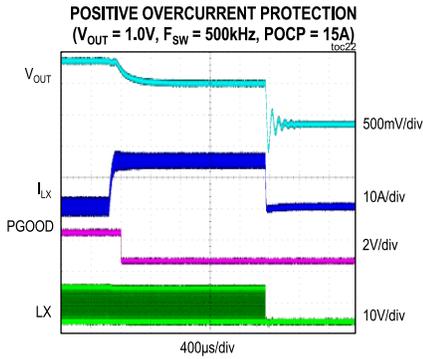
Note 3: Guaranteed by design.

Typical Operating Characteristics

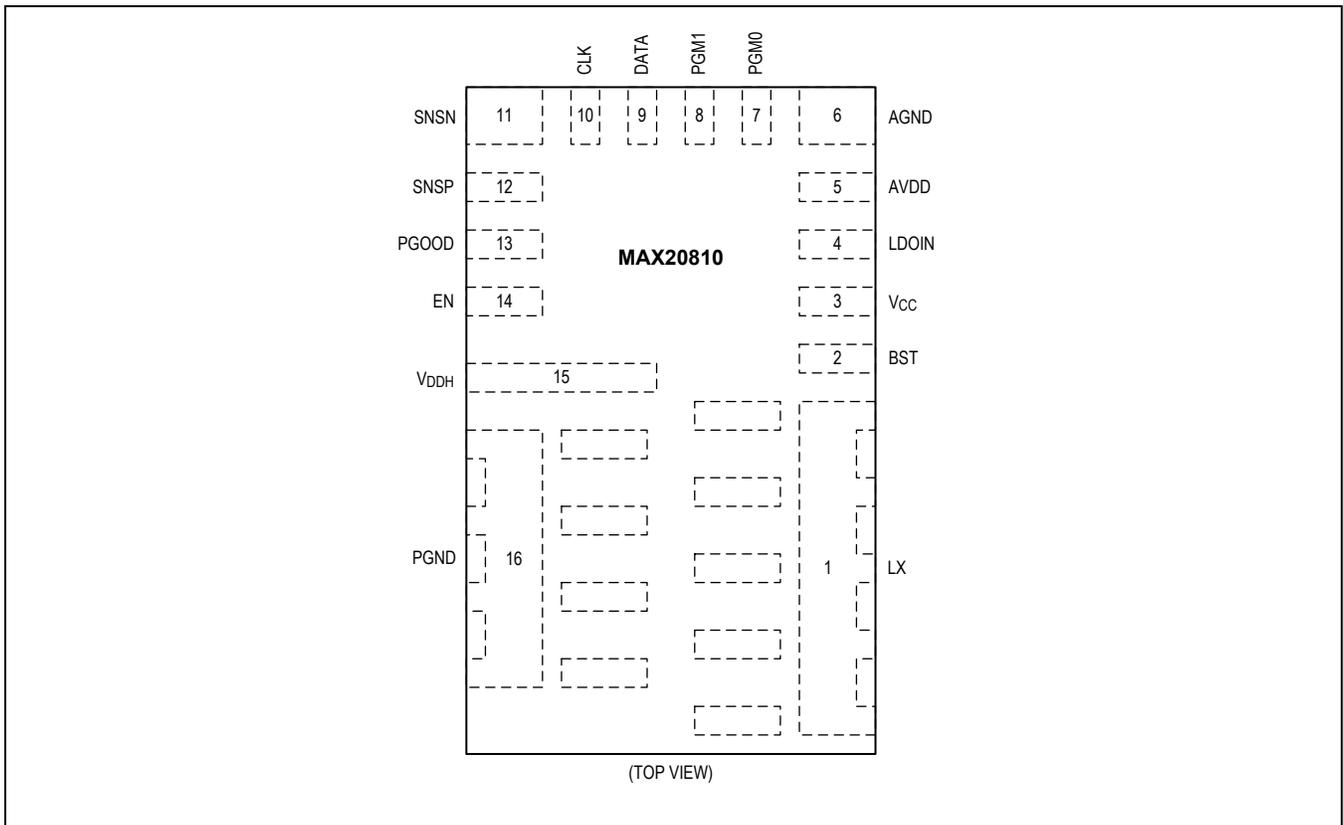
(*Typical Application Circuit*, tested on MAX20810EVKIT#, $V_{DDH} = 12V$, $F_{SW} = 500kHz$, $T_A = +25^\circ C$, Inductor = PA5034.XXXHLT or PA4987.102HL for $V_{OUT} > 2.5V$, unless otherwise noted.)







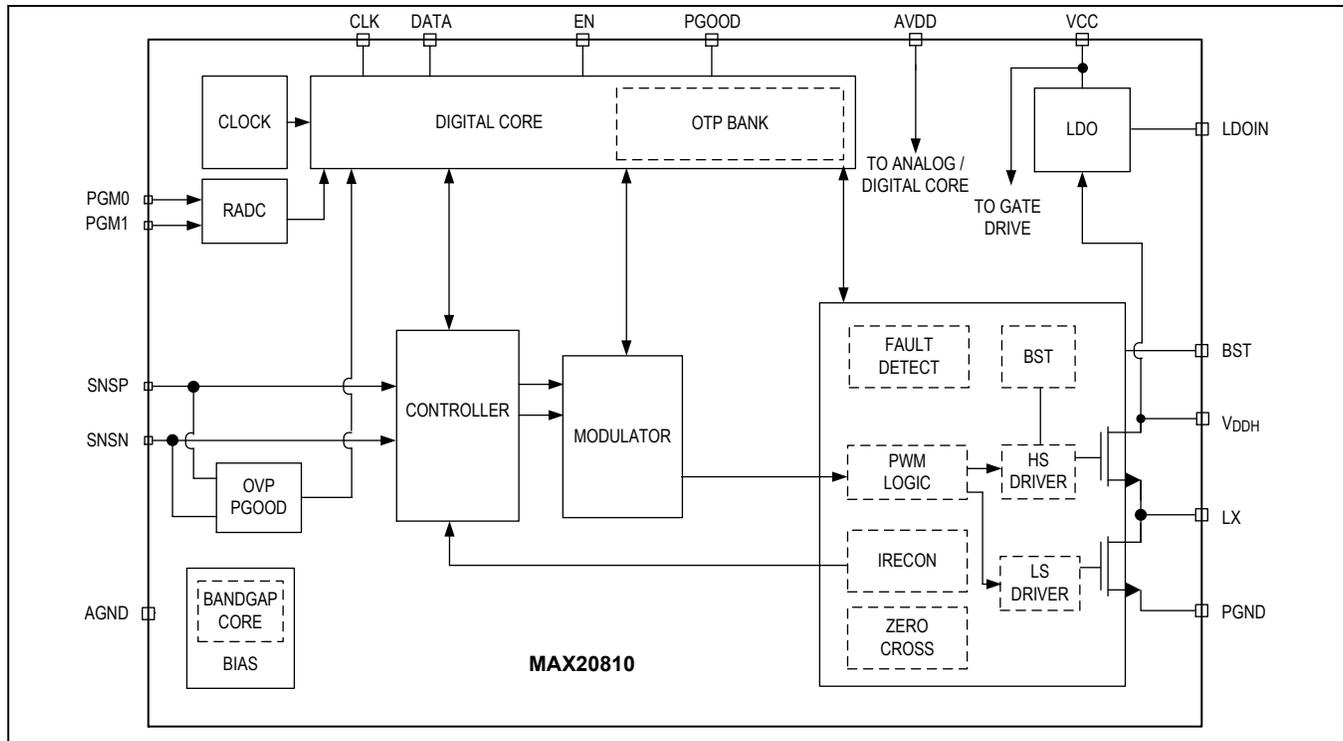
Pin Configuration



Pin Descriptions

PIN	NAME	FUNCTION
1	LX	Switching Node. Connect LX directly to the output inductor.
2	BST	Bootstrap Pin. Connect a 0.47 μ F ceramic capacitor from BST to LX.
3	V _{CC}	Internal 1.8V LDO Output. Connect a 4.7 μ F or greater ceramic capacitor from V _{CC} to PGND.
4	LDOIN	Optional 2.5V to 5.5V LDO Input Supply. Leave this pin floating if unused.
5	AVDD	1.8V Supply for Analog Circuitry. Connect a 2.2 Ω to 4.7 Ω resistor from AVDD to V _{CC} . Connect a 1 μ F or greater ceramic capacitor from AVDD to AGND.
6	AGND	Analog Ground.
7	PGM0	Program Input. Connect this pin to ground though a programming resistor.
8	PGM1	Program Input. Connect this pin to ground though a programming resistor.
9	DATA	PMBus Data
10	CLK	PMBus Clock
11	SNSN	Output Voltage Remote Sense Negative Input.
12	SNSP	Output Voltage Remote Sense Positive Input Pin. Connect SNSP to output voltage at the load. A resistive voltage divider can be inserted between the output and SNSP to regulate the output above the reference voltage.
13	PGOOD	Open-Drain Power Good Output.
14	EN	Output Enable.
15	V _{DDH}	Regulator Input Supply.
16	PGND	Power Ground.

Block Diagram



Detailed Description

Control Architecture

Fixed-Frequency Peak Current-Mode Control Loop

The MAX20810 control loop is based on fixed-frequency peak current-mode control architecture. A simplified control architecture is shown in [Figure 1](#). The loop contains an error amplifier stage, internal voltage loop compensation network, current sense, internal slope compensation, and a PWM modulator that generates the PWM signals to drive high-side and low-side MOSFETs. The device has a default 0.5V reference voltage (V_{REF}). The reference voltage can be adjusted by the PMBus `VOUT_COMMAND` from 0.4V to 0.8V with 1.95mV resolution (Refer to the [UG7185: MAX20830/MAX20815/MAX20810 PMBus Command Set User Guide](#)). The difference of V_{REF} and the sensed output voltage is amplified by the first error amplifier. Its output voltage (V_{ERR}) is used as the input of the voltage loop compensation network. The output of the compensation network (V_{COMP}) is fed to a PWM comparator with current-sense signal (V_{ISENSE}) and the slope compensation (V_{RAMP}). The output of the PWM comparator is the input of the PWM modulator. The turning on of the high-side MOSFET is aligned with an internal clock. It can either be a fixed-frequency clock or a phase-shifted clock if AMS is enabled.

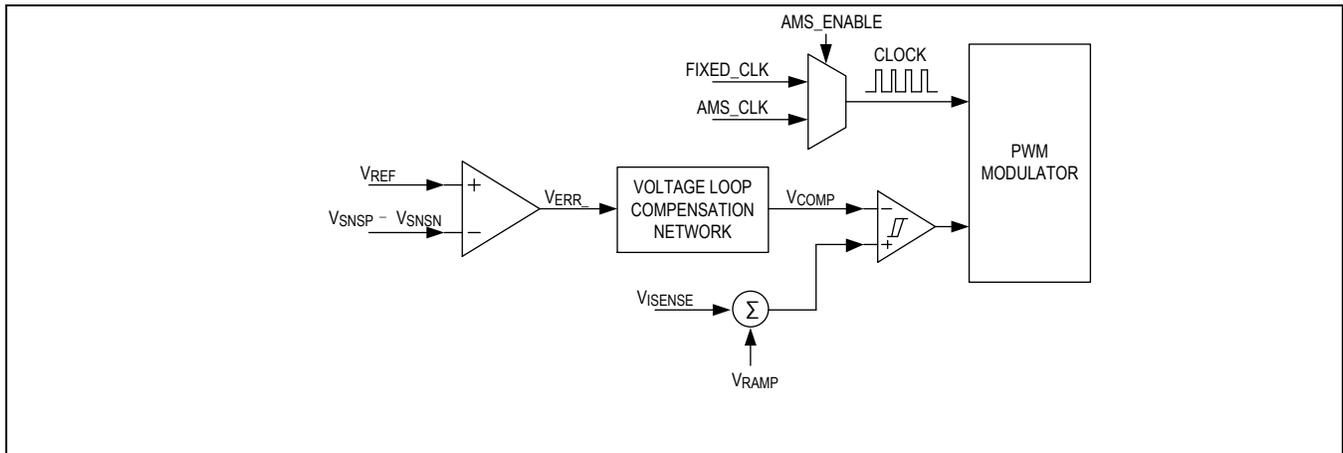


Figure 1. Simplified Control Architecture

Advanced Modulation Scheme (AMS)

The MAX20810 offers a selectable AMS to provide improved transient response. The AMS provides a significant advantage over conventional fixed-frequency PWM schemes. Enabling the AMS feature allows for modulation at both leading and trailing edges, which results a temporary increase or decrease of the switching frequency during large load transients. [Figure 2](#) shows the scheme to include leading-edge modulation to the traditional trailing-edge modulation when AMS is enabled in the device. The modulation scheme allows the turn on and off with minimal delay. Since the total inductor current increases very quickly, thus satisfying the load demand, the current drawn from the output capacitors is reduced. With AMS enabled, the system closed-loop bandwidth can be extended without phase-margin penalty. As a result, the output capacitance can be minimized.

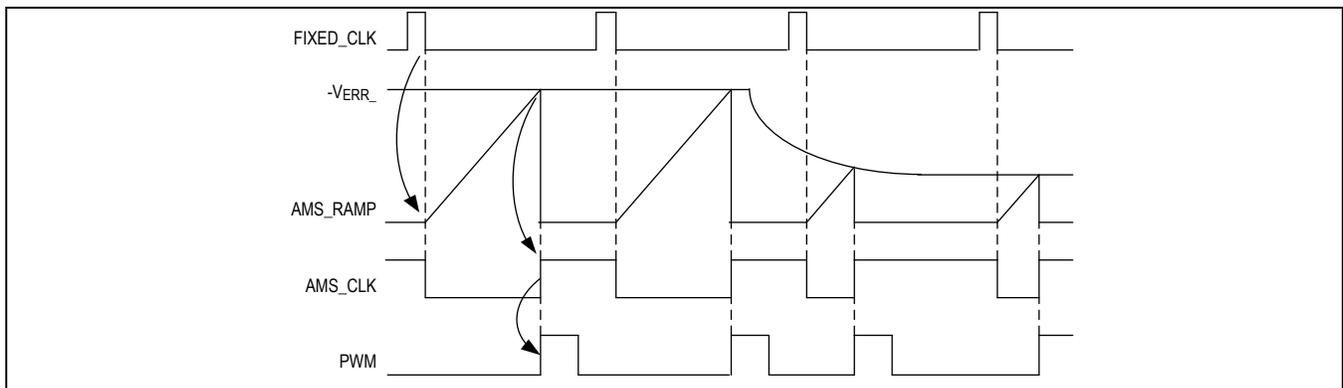


Figure 2. AMS Operation

Discontinuous Current Mode (DCM) operation

The discontinuous current mode (DCM) operation is an optional feature to improve light-load efficiency. The device has a DCM current-detection comparator to monitor the inductor valley current while operating in CCM. At light load, if the inductor valley current is below the DCM comparator threshold for 48 consecutive cycles, the device transition seamlessly to DCM. Once in DCM, the switching frequency decreases as load decreases. The device transitions back to CCM operation as soon as the inductor valley current is higher than 0A.

For MAX20810 DCM is by default disabled, it can be enabled by the PMBus commands (Refer to the [UG7185: MAX20830/MAX20815/MAX20810 PMBus Command Set User Guide](#)).

Internal Linear Regulator

The device contains an internal 1.8V linear regulator (LDO). The 1.8V LDO output voltage on V_{CC} is derived from the V_{DDH} pin by default. To improve efficiency, an optional 2.5V to 5.5V bias input supply can be applied on the LDOIN pin so that the 1.8V voltage on V_{CC} is converted from the LDOIN pin instead. The optional LDOIN bias input supply can be applied or removed anytime during regulation without affecting the operation.

The 1.8V voltage on the V_{CC} pin supplies the current to the MOSFET drivers. A decoupling capacitor of at least 4.7 μ F must be connected between V_{CC} and PGND. The AVDD pin of the device also requires a 1.8V supply to power the device's internal analog circuitry. A 2.2 Ω to 4.7 Ω resistor must be connected between AVDD and V_{CC} . A 1 μ F or greater decoupling capacitor must be used between AVDD and AGND.

Startup and Shutdown

The startup and shutdown timing is shown in [Figure 3](#). When the AVDD pin voltage is above its rising UVLO threshold, the device goes through an initialization procedure. Configuration settings on the PGM_ pins are read. Once initialization is complete, the device detects the V_{DDH} UVLO and EN status. When both are above their rising thresholds, soft-start begins and switching is enabled. The output voltage of the enabled output starts to ramp up. The soft-start ramp time is 1ms. If there are no faults, the open-drain PGOOD pin is released from being held low after the soft-start ramp is complete. The device supports smooth startup with the output prebiased.

During operation, if either V_{DDH} UVLO or EN falls below its thresholds, switching is stopped immediately. The output voltage is discharged by the load current.

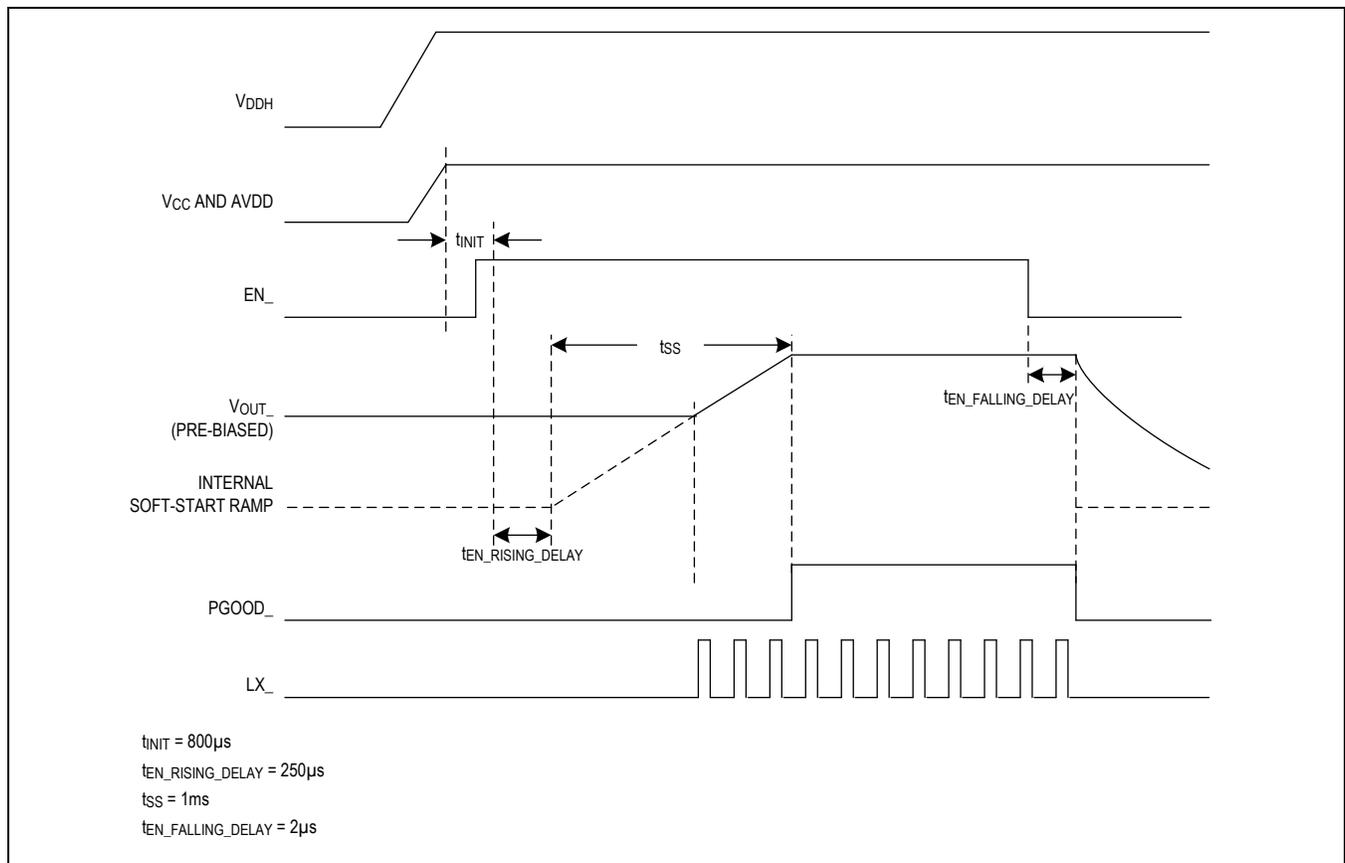


Figure 3. Startup and Shutdown Timing

Fault Handling

Input Undervoltage Lockout (V_{DDH} UVLO)

The MAX20810 internally monitors the V_{DDH} voltage level. When the input supply voltage is below the UVLO threshold, the device stops switching and drives the PGOOD pin low. The device restarts after 20ms if the UVLO status is cleared. See [Startup and Shutdown](#) for startup sequence.

Output Overvoltage Protection (OVP)

The feedback voltage on $V_{SNSP} - V_{SNSN}$ is monitored for output overvoltage once the soft-start ramp is complete. If the feedback voltage is above the OVP threshold beyond the OVP deglitch filtering delay, the device stops switching and drives PGOOD pin low. The device restarts after 20ms if the OVP status is cleared.

Positive Overcurrent Protection (POCP)

The device's peak current mode control architecture provides inherent current limiting and short-circuit protection. The inductor current is continuously monitored while switching. The inductor peak current is limit on a cycle-by-cycle basis. In each switching cycle, once the sensed inductor current exceeds the POCP threshold, the device turns off the high-side MOSFET and turns on the low-side MOSFET to allow the inductor current to be discharged by output voltage. An up-down counter is used to accumulate the number of consecutive POCP events each switching cycle. If the counter exceeds 1024, the device stops switching and drives the PGOOD pin low. POCP is a hiccup protection and the device restarts after 20ms.

The MAX20810 offers four POCP thresholds (15A, 13A, 11A, and 9A), which can be selected by the PGM0 pin (see the [Pin-Strap Programmability](#)). Due to POCP deglitch delay, for a specific application use case, the actual POCP threshold should be higher (see the [Output Inductor Selection](#)).

Negative Overcurrent Protection (NOCP)

The device also has negative overcurrent protection against inductor valley current. The NOCP threshold is -79% of the POCP threshold. In each switching cycle, once the sensed inductor current exceeds the NOCP threshold, the device turns off the low-side MOSFET and turns on the high-side MOSFET for a fixed 180ns time to allow the inductor current to be charged by input voltage. Same as the POCP, an up-down counter is used to accumulate the number of consecutive NOCP events. If the counter exceeds 1024, the device stops switching and drives the PGOOD pin low. NOCP is a hiccup protection and the device restarts after 20ms.

Overtemperature Protection (OTP)

The overtemperature protection threshold is 155°C with 20°C hysteresis. If the junction temperature reaches OTP threshold during operation, the device stops switching and drives the PGOOD pin low. The device restarts after 20ms if the OTP status is cleared.

Pin-Strap Programmability

The MAX20810 has two program pins (PGM0 and PGM1) to set some of the key configurations of the device. The PGM_ values are read during startup initialization. PGM0 and PGM1 each has 32 detection levels. A pin-strap resistor is connected from the PGM_ pin to AGND to select one of the 32 codes. PGM0 is used to select the POCP level and PMBus address. PGM1 is used to select the switching frequency and a predefined scenario which is defined in [Table 3](#).

Table 1. PGM0, POCP, and PMBus Address Selections

PGM0 CODES	R _{PGM0} (Ω)	POCP (A)	PMBus ADDRESS
0	95.3	15	0x38h
1	200		0x39h
2	309		0x3Ah
3	422		0x3Bh
4	536		0x3Ch
5	649		0x3Dh
6	768		0x3Eh
7	909		0x3Fh
8	1050	13	0x38h
9	1210		0x39h
10	1400		0x3Ah
11	1620		0x3Bh
12	1870		0x3Ch
13	2150		0x3Dh
14	2490		0x3Eh
15	2870		0x3Fh
16	3740	11	0x38h
17	8060		0x39h
18	12400		0x3Ah
19	16900		0x3Bh
20	21500		0x3Ch
21	26100		0x3Dh
22	30900		0x3Eh
23	36500		0x3Fh
24	42200	9	0x38h
25	48700		0x39h
26	56200		0x3Ah
27	64900		0x3Bh
28	75000		0x3Ch
29	86600		0x3Dh
30	100000		0x3Eh
31	115000		0x3Fh

Table 2. PGM1 Switching Frequency and Scenario Selection

PGM1 CODES	R _{PGM1} (Ω)	SWITCHING FREQUENCY (kHz)	SCENARIO #
0	95.3	500	A
1	200		B
2	309		C
3	422		D
4	536		E
5	649		F
6	768	600	A
7	909		B
8	1050		C
9	1210		D
10	1400		E
11	1620		F
12	1870	750	A
13	2150		B
14	2490		C
15	2870		D
16	3740		E
17	8060		F
18	12400	1000	A
19	16900		B
20	21500		C
21	26100		D
22	30900		E
23	36500		F
24	42200	1200	A
25	48700		B
26	56200		C
27	64900		D
28	75000		E
29	86600		F
30	100000	2000	A
31	115000		B

The MAX20810 has six predefined scenarios as summarized in [Table 3](#), which can be selected by a pin-strap resistor connected from the PGM1 pin to AGND. See the [Voltage Loop Gain](#) section for information about how to select the voltage loop gain resistance (R_{VGA}) for optimized control loop performance. For each scenario, the AMS option can also be selected.

Table 3. Predefined Scenarios

SCENARIO #	R _{VGA} (kΩ)	AMS OPTION
A	15.7	Disabled
B	22.7	Disabled
C	22.7	Enabled
D	26.8	Enabled
E	31.3	Enabled
F	44.8	Enabled

PMBus Interface

PMBus is an industry standard that defines a means of communication with power conversion devices. It is comprised of an industry standard SMBus serial interface and the PMBus command language. The MAX20810 supports the PMBus interface to communicate with a host (master) device. The device PMBus address is selected by a pin-strap resistor connected from the PGM0 pin to AGND (see the [Pin-Strap Programmability](#)). [Table 4](#) shows the supported PMBus commands. For the detailed PMBus command definition and the application note, refer to the [UG7185: MAX20830/MAX20815/MAX20810 PMBus Command Set User Guide](#).

Table 4. Supported PMBus Commands

COMMAND CODE	COMMAND NAME	DESCRIPTION	TYPE	DATA FORMAT	FACTORY VALUE
0x01	OPERATION	Output enable/disable	R/W Byte	Bit field	0x80
0x02	ON_OFF_CONFIG	EN pin and PMBus operation command setting	R/W Byte	Bit field	0x1F
0x03	CLEAR_FAULTS	Clear any fault bits that have been set	Send Byte		N/A
0x10	WRITE_PROTECT	Level of protection provided by the device against accidental changes	R/W Byte	Bit field	0x20
0x19	CAPABILITY	Summary of PMBus optional communication protocols supported by this device	R Byte	Bit field	0xA0
0x20	VOUT_MODE	Output voltage data format and mantissa exponent	R Byte	Bit field	0x17
0x21	VOUT_COMMAND	Reference voltage setpoint	R/W Word	ULINEAR16	0x0100
0x24	VOUT_MAX	Upper limit of reference voltage setpoint	R/W Word	ULINEAR16	0x019A
0x78	STATUS_BYTE	One byte summary of the unit's fault condition	R Byte	Bit field	N/A
0x79	STATUS_WORD	Two bytes summary of the unit's fault condition	R Word	Bit field	N/A
0x7A	STATUS_VOUT	Output voltage fault and warning status	R Byte	Bit field	N/A
0x7B	STATUS_IOUT	Output current fault and warning status	R Byte	Bit field	N/A
0x7C	STATUS_INPUT	Input voltage fault and warning status	R Byte	Bit field	N/A
0x7D	STATUS_TEMPERATURE	IC junction temperature fault and warning status	R Byte	Bit field	N/A
0x7E	STATUS_CML	Communication fault and warning status	R Byte	Bit field	N/A
0x80	STATUS_MFR_SPECIFIC	Manufacture specific fault and warning status	R Byte	Bit field	N/A
0x88	READ_VIN	Input voltage telemetry	R Word	LINEAR11	N/A
0x8B	READ_VOUT	Feedback voltage telemetry	R Word	ULINEAR16	N/A
0x8C	READ_IOUT	Output current telemetry	R Word	LINEAR11	N/A
0x8D	READ_TEMPERATURE_1	IC junction temperature telemetry	R Word	LINEAR11	N/A
0xAD	IC_DEVICE_ID	Device root part number	R Block	ASCII	"MAX20810"
0xAE	IC_DEVICE_REV	Device revision code	R Block	ASCII	N/A
0xD0	MFR_PINSTRAP	Manufacture specific device operating configurations	R/W Byte	Bit field	N/A
0xD1	MFR_SCENARIO_0	Manufacture specific device operating configurations	R/W Byte	Bit field	N/A
0xD2	MFR_SCENARIO_1	Manufacture specific device operating configurations	R/W Byte	Bit field	N/A
0xD3	MFR_SCENARIO_2	Manufacture specific device operating configurations	R/W Byte	Bit field	N/A

Reference Design Procedure

Output Voltage Sensing

The MAX20810 has a default 0.5V reference voltage. The reference voltage can be adjusted by the PMBus VOUT_COMMAND from 0.4V to 0.8V with 1.95mV resolution (refer to the [UG7185: MAX20830/MAX20815/MAX20810 PMBus Command Set User Guide](#)). When the desired output voltage is higher than VREF, it is required to use a resistor-dividers RFB1 and RFB2 to sense the output voltage (See the [Typical Application Circuit](#)). It is recommended that the value RFB2 does not exceed 5kΩ. The resistor-divider ratio is given by the following equation:

$$V_{OUT} = V_{REF} \times \left(1 + \frac{R_{FB1}}{R_{FB2}} \right)$$

where:

VOUT = Output voltage

VREF = Reference voltage

RFB1 = Top divider resistor

RFB2 = Bottom divider resistor

Switching Frequency Selection

The MAX20810 offers a wide range of selectable switching frequencies from 500kHz to 2MHz. The selection of switching frequency can be optimized for different applications. Higher switching frequencies are recommended for applications prioritizing solution size so that the value and size of output LC filter can be reduced. Lower switching frequencies are recommended for applications prioritizing efficiency and thermal dissipation due to reduced switching losses. It is required that the frequency be selected so that the minimum controllable on-time and minimum controllable off-time are not violated. The maximum recommended switching frequency is calculated by the following equation:

$$f_{SWMAX} = \text{MIN} \left\{ \frac{V_{OUT}}{t_{ONMIN} \times V_{DDHMAX}}, \frac{V_{DDHMIN} - V_{OUT}}{t_{OFFMIN} \times V_{DDHMIN}} \right\}$$

where:

fSWMAX = Maximum selectable switching frequency

VDDHMAX = Maximum input voltage

VDDHMIN = Minimum input voltage

tONMIN = Minimum controllable on-time

tOFFMIN = Minimum controllable off-time

The MAX20810 internally has a slope compensation applied to the current loop during on-time to guarantee stability and improve noise immunity. To avoid the slope compensation saturating the current loop, it is required that the maximum on-time be limited by:

$$T_{ONMAX} = \frac{5\text{pF} \left[800\text{mV} \times \left(I_{OUTMAX} + \frac{I_{RIPPLE}}{2} \right) \times \frac{1.6\Omega}{62.5} \right]}{1.89\mu\text{A}}$$

where:

TONMAX = Maximum on-time of the high-side MOSFET

IOUTMAX = Maximum load current

IRIPPLE = Inductor current ripple peak-to-peak value

The minimum recommended switching frequency is calculated by the following equation:

$$f_{\text{SWMIN}} = \frac{V_{\text{OUT}}}{T_{\text{ONMAX}} \times V_{\text{DDHMIN}}}$$

where:

f_{SWMIN} = Minimum selectable switching frequency

Due to system noise injection, even at steady-state operation, typically the LX rising and falling edges would have some random jittering noise. The selection of the switching frequency (f_{SW}) should take into consideration the jittering and be higher than f_{SWMIN} and lower than f_{SWMAX} . To improve the LX jittering, it is recommended to use smaller inductor values and lower voltage loop gain to minimize the noise sensitivity.

Output Inductor Selection

The output inductor has an important influence on the overall size, cost, and efficiency of the voltage regulator. Since the inductor is typically one of the larger components in the system, a minimum inductor value is particularly important in space-constrained applications. Smaller inductor values also permit faster transient response, reducing the amount of output capacitance needed to maintain transient tolerance. Typically, the output inductor is selected so that the inductor current ripple is 20% to 40% of the maximum load current for optimized performance. To improve current loop noise immunity, it is recommended that the inductor current ripple is at least 2A. The inductor value is calculated by the following equation:

$$L = \frac{V_{\text{OUT}}(V_{\text{DDH}} - V_{\text{OUT}})}{V_{\text{DDH}} \times I_{\text{RIPPLE}} \times f_{\text{SW}}}$$

where:

V_{DDH} = Input voltage

I_{RIPPLE} = Inductor current ripple peak-to-peak value

The inductor should also be selected so that maximum load current delivery can be guaranteed by the selected POCP threshold. The MAX20810 offers four POCP thresholds (15A, 13A, 11A, and 9A), which can be selected by the PGM0 pin (see the [Pin-Strap Programmability](#)). Due to deglitch delay from the POCP comparator tripping to the high-side MOSFET turning off for a specific application use case, the adjusted POCP threshold should take into consideration the inductor value, input voltage and output voltage, which can be calculated by the following equation:

$$\text{POCP}_{\text{ADJUST}} = \text{POCP} + \frac{(V_{\text{DDH}} - V_{\text{OUT}}) \times t_{\text{POCP}}}{L}$$

where:

$\text{POCP}_{\text{ADJUST}}$ = Adjusted POCP threshold

POCP = POCP level specified in the [Electrical Characteristics](#) table

t_{POCP} = POCP deglitch delay (40ns typical)

It needs to be verified that the peak inductor current in normal operation does not exceed the minimum adjusted POCP threshold:

$$I_{\text{OUTMAX}} + \frac{I_{\text{RIPPLE}}}{2} < \text{POCP}_{\text{ADJUST(MIN)}}$$

where:

I_{OUTMAX} = Maximum load current

$\text{POCP}_{\text{ADJUST(MIN)}}$ = Minimum adjusted POCP threshold, calculated with the minimum value of the POCP threshold

[Table 5](#) shows some suitable inductor part numbers which are verified on the MAX20810 evaluation kit to offer optimal performance.

Table 5. Recommended Inductors

COMPANY	VALUE (nH)	I _{SAT} (A)	R _{DC} (mΩ)	FOOTPRINT (mm)	HEIGHT (mm)	PART NUMBER
Eaton	220	58	0.17	10.8 × 8.0	8.0	FP1008R5-R220-R
Eaton	270	44	0.17	10.8 × 8.0	8.0	FP1008R5-R270-R
Pulse	330	40	0.4	10.0 × 7.0	10.0	PA5034.331HLT
Pulse	470	30	0.4	10.0 × 7.0	10.0	PA5034.471HLT
Pulse	1000	20.5	0.81	10.0 × 7.0	10.0	PA4987.102HLT

Output Capacitor Selection

One major factor in determining the total required output capacitance is the output-voltage ripple. To meet the output-voltage ripple requirement, the minimum output capacitance should satisfy the following equation:

$$C_{OUT} \geq \frac{I_{RIPPLE}}{8 \times f_{SW} \times (V_{OUTRIPPLE} - ESR \times I_{RIPPLE})}$$

where:

$V_{OUTRIPPLE}$ = Maximum allowed output-voltage ripple

ESR = ESR of output capacitors

The other important factors in determining the total required output capacitance are the maximum allowable output voltage overshoot and undershoot during load transients. For a given loading or unloading current step, the minimum required output capacitance should also satisfy the following equation:

$$C_{OUT} \geq \text{MAX} \left\{ \frac{\left(\Delta I + \frac{I_{RIPPLE}}{2} \right)^2 \times L}{2 \times \Delta V_{OUT} \times (V_{DDH} - V_{OUT})}, \frac{\left(\Delta I + \frac{I_{RIPPLE}}{2} \right)^2 \times L}{2 \times \Delta V_{OUT} \times V_{OUT}} \right\}$$

where:

C_{OUT} = Output capacitance

ΔI = Loading or unloading current step

ΔV_{OUT} = Maximum allowed output voltage undershoot or overshoot

Input Capacitor Selection

The input capacitance selection is determined by the input voltage ripple requirement. The minimum required input capacitance is estimated by the following equation:

$$C_{IN} \geq \frac{I_{OUT(MAX)} \times V_{OUT}}{f_{SW} \times V_{DDH} \times V_{INPP}}$$

where:

$I_{OUT(MAX)}$ = Maximum output current

V_{OUT} = Output voltage

f_{SW} = Switching frequency

V_{INPP} = Peak-to-peak input voltage ripple

Besides the minimum required input capacitance, it is recommended to also place 0.1μF and 1μF high-frequency decoupling capacitors next to the V_{DDH} pin to suppress the high-frequency switching noises.

Voltage Loop Gain

For stability purpose, it is recommended that the voltage loop bandwidth (BW) be lower than 1/5 of the switching frequency. Consider the case of using MLCC output capacitors that have nearly ideal impedance characteristics in the frequency range of interest with negligible ESR and ESL. The voltage loop BW can be estimated with the following equation:

$$BW = \frac{R_{FB2}}{R_{FB2} + R_{FB1}} \times \frac{R_{VGA}}{10k\Omega} \times \frac{1}{2\pi \times 8m\Omega \times C_{OUT}}$$

where:

R_{VGA} = The voltage loop gain resistance, which is set by the scenario selected ([Table 3](#))

Typical Reference Designs

See the [Typical Application Circuits](#) for examples of reference schematics. Reference design examples for some common output voltages are shown in [Table 6](#).

Table 6. Reference Design Examples

V _{OUT} (V)	I _{OUT} (A)	f _{SW} (kHz)	R _{FB1} (kΩ)	R _{FB2} (kΩ)	PGM0 (Ω)	PGM1 (Ω)	L (nH)	C _{IN}	C _{OUT}
0.8	10	750	1.82	3.01	95.3	2150	330	2 × 10μF + 1μF + 0.1μF	4 × 100μF
0.9	10	750	2.40	3.01	95.3	2150	330	2 × 10μF + 1μF + 0.1μF	4 × 100μF
1.0	10	750	3.01	3.01	95.3	2150	330	2 × 10μF + 1μF + 0.1μF	4 × 100μF
1.2	10	750	4.22	3.01	95.3	2150	470	2 × 10μF + 1μF + 0.1μF	4 × 100μF
1.8	8	1000	7.87	3.01	1050	16900	470	2 × 10μF + 1μF + 0.1μF	3 × 100μF
3.3	7	1200	16.9	3.01	3740	48700	1000	2 × 10μF + 1μF + 0.1μF	3 × 100μF
5.0	6	2000	22.6	2.49	42200	115000	1000	2 × 10μF + 1μF + 0.1μF	3 × 47μF

PCB Layout Guidelines

- For electrical and thermal reasons, the second layer from the top and bottom of the PCB should be reserved for power ground (PGND) planes.
- The input decoupling capacitor should be located the closest to the IC and no more than 40mils from the V_{DDH} pin.
- The V_{CC} decoupling capacitors should be connected to PGND and placed as close as possible to V_{CC} pin.
- An analog ground copper polygon or island should be used to connect all analog control-signal grounds. This “quiet” analog ground copper polygon or island should be connected to the PGND through a single connection close to the AGND pin. The analog ground can be used as a shield and ground reference for the control signals.
- The AVDD decoupling capacitors should be connected to AGND and placed as close as possible to AVDD pin.
- The boost capacitors should be placed as close as possible to LX and BST pins on the same side of the PCB as the IC.
- The feedback resistor-divider and optional external compensation network should be placed close to the IC to minimize the noise injection.
- Output voltage should be sensed with the differential remote sense lines routed directly from an output capacitor from the load point, shielded by the ground plane, and be kept away from the switching node and the inductor.
- Multiple vias are recommended for all paths that carry high currents and for heat dissipation.
- The input capacitors and output inductors should be placed near the IC and the traces to the components should be kept as short and wide as possible to minimize parasitic inductance and resistance.

Ordering Information

Part Number	Temp Range	Pin-Package
MAX20810AFE+	-40°C to +125°C	16 FC2QFN
MAX20810AFE+T	-40°C to +125°C	16 FC2QFN

+Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	11/22	Release for Market Intro	—

